



## iCEblink40 iCE40HX1K Evaluation Kit

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### User's Guide

## Introduction

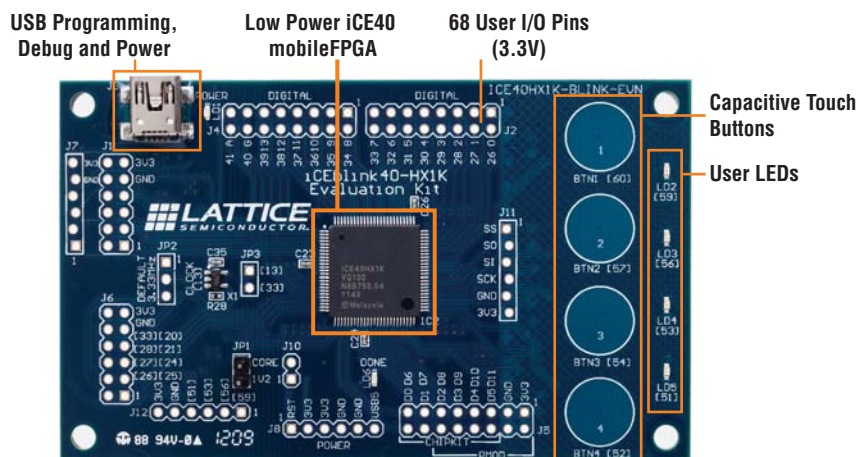
Thank you for choosing the Lattice Semiconductor iCEblink™40 HX1K Evaluation Kit.

This guide describes how to begin using the iCEblink40 Evaluation Kit, an easy-to-use platform for rapidly prototyping designs using the iCE40 mobileFPGA™.

## Features

- High-performance, low-power iCE40HX1K mobileFPGA
- USB programming, debugging, virtual I/O functions, and power supply
- Four user LEDs
- Four capacitive-touch buttons
- 3.3 MHz clock source
- 1Mbit SPI serial configuration PROM
- Supported by Lattice iCEcube2™ design software
- 68 LVCMOS/LVTTL (3.3V) digital I/O connections on 0.1" through-hole connections
- Supports third-party I/O expansion boards and modules, including 3.3V Arduino Shield boards (requires additional sockets, not supplied)

**Figure 1. iCEblink40 HX1K Evaluation Board and Major Hardware Features**



## Software Requirements

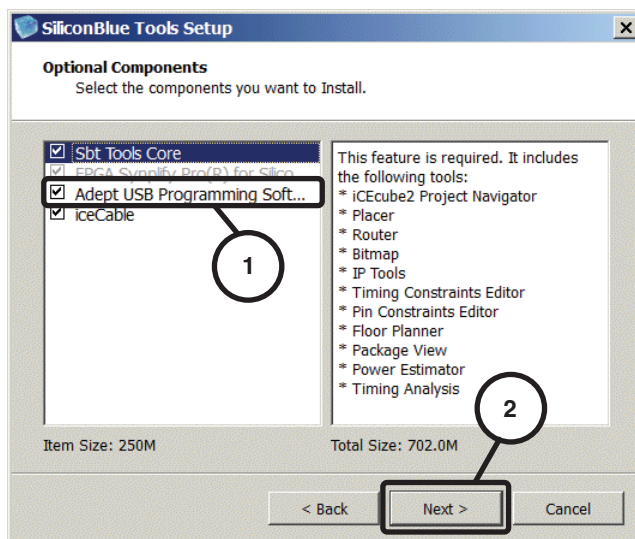
Before using the iCEblink40 board, please be sure to download and install iCEcube2 Release 2011.12 or later. This and later versions include the programming software for the iCEblink40 board. Currently, the programming software is only available for the Windows operating system.

<http://www.latticesemi.com/products/designsoftware/icecube2/downloads.cfm>

During the installation process, be sure to install the Adept USB Programming Software, as shown in Figure 2.

1. Make sure that **Adept USB Programming Software** is checked. This is the default setting.
2. Click **Next**.

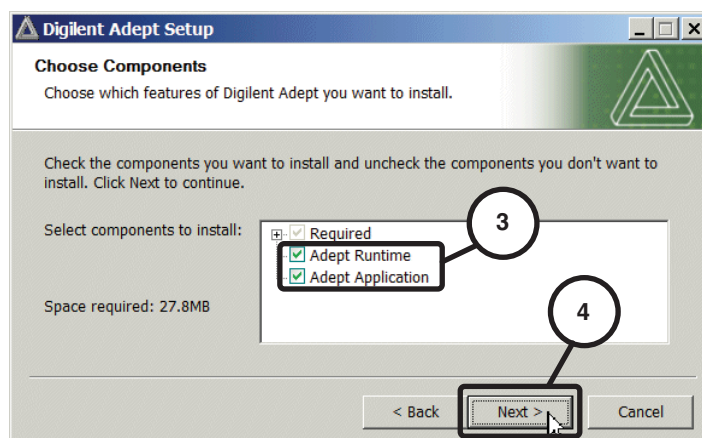
**Figure 2. Select the Adept Programming Software for Installation**



A few steps later, select the installation for the Adept programming software, as shown in Figure 3.

3. Make sure that both the **Adept Runtime** and **Adept Application** options are checked, which are the default settings.
4. Click **Next**.

**Figure 3. Adept Setup Options**



## Connecting to the iCEblink40 Evaluation Board

Before connecting the iCEblink40 board, be sure to download and install a supported version of the iCEcube2 software.

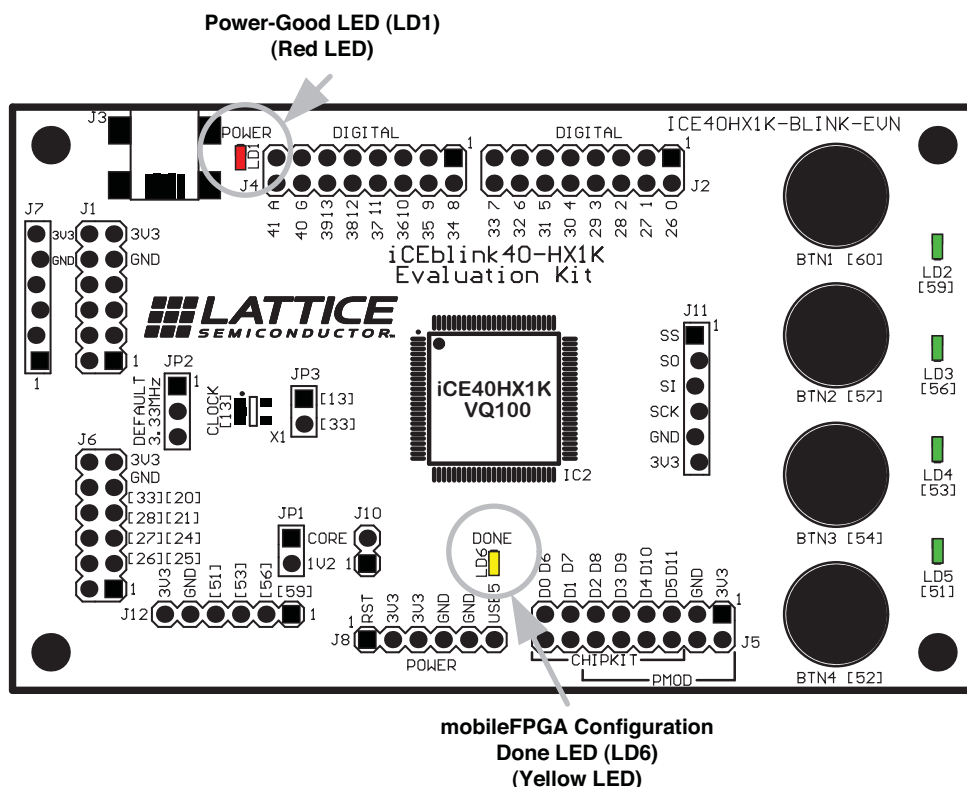
Connect the iCEblink40 evaluation board to your PC using the USB cable provided. The USB connector on the board is labeled with reference designator J3 and is located in the upper left corner. Once connected, the red power-good LED (LD1) adjacent to the USB connector illuminates. See Figure 4 to locate the power-good LED.

## Power and Configuration Status LEDs

The iCEblink40 evaluation board has two status LEDs, as shown in Figure 4. These two status LEDs indicate the current status of the iCEblink40 board, as listed in Table 1. The red LED, LD1, located near the USB connector indicates if the USB power supply, the 3.3V supply, and the 1.2V supply are within the specified ranges.

The yellow LED, LD6, located below the mobileFPGA indicates whether the mobileFPGA is configured properly. This LED lights up when the FPGA is correctly loaded with a valid bitstream.

**Figure 4. iCEblink40 Status LEDs**



**Table 1. iCEblink40 Status LED Descriptions**

| Power-Good LED (LD1) | Configuration DONE LED (LD6) | Description   |
|----------------------|------------------------------|---|
| On                   | On                           | The board is powered, the mobileFPGA successfully configured and the mobileFPGA application is operating.   |
| Off                  | Off                          | Board is unpowered. Connect the board to a computer USB port, a powered hub, or a USB-based wall plug.<br>If board is plugged in and previously operating, indicates that an SPI Flash programming operation is in progress |
| On                   | Off                          | The board is powered but the mobileFPGA is not yet configured.<br><b>ACTION:</b> Program the onboard SPI Flash PROM with a valid mobileFPGA configuration bitstream.  |
| Off                  | On                           | <b>ERROR:</b> The board is powered but there is a problem with the USB power supply or with the on-board regulator.   |

## Pre-programmed Demonstration Design

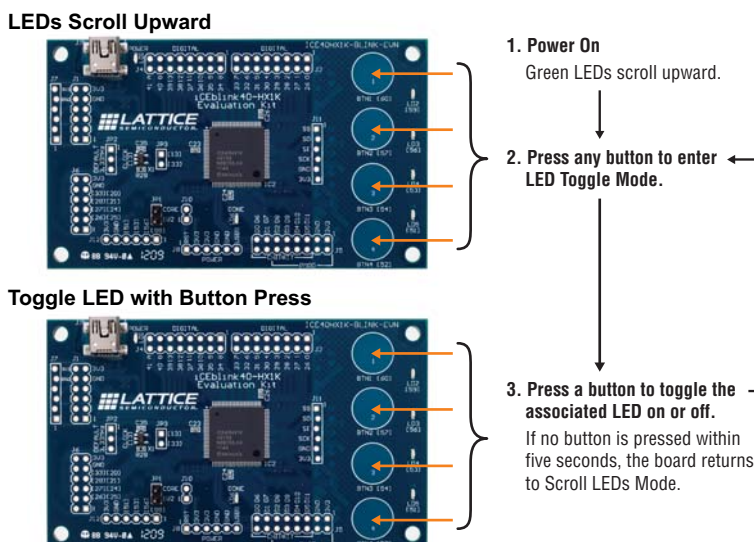
The iCEblink40 board comes preprogrammed with a demonstration application. The application supports two interfaces.

1. Control the LEDs from the four capacitive touch buttons on the board itself.
2. Control the LEDs and other internal logic using the USB-based I/O expansion interface.

## Operating the Capacitive Touch Buttons

Upon power up, the green LEDs on the board scroll in an upward pattern, as described in Figure 5. Pressing any of the capacitive touch buttons stops the LEDs from scrolling and places the board in a different operating mode.

**Figure 5. Preprogrammed Demonstration Design**



In the second operating mode, toggle individual LEDs on and off by pressing the associated capacitive touch button.

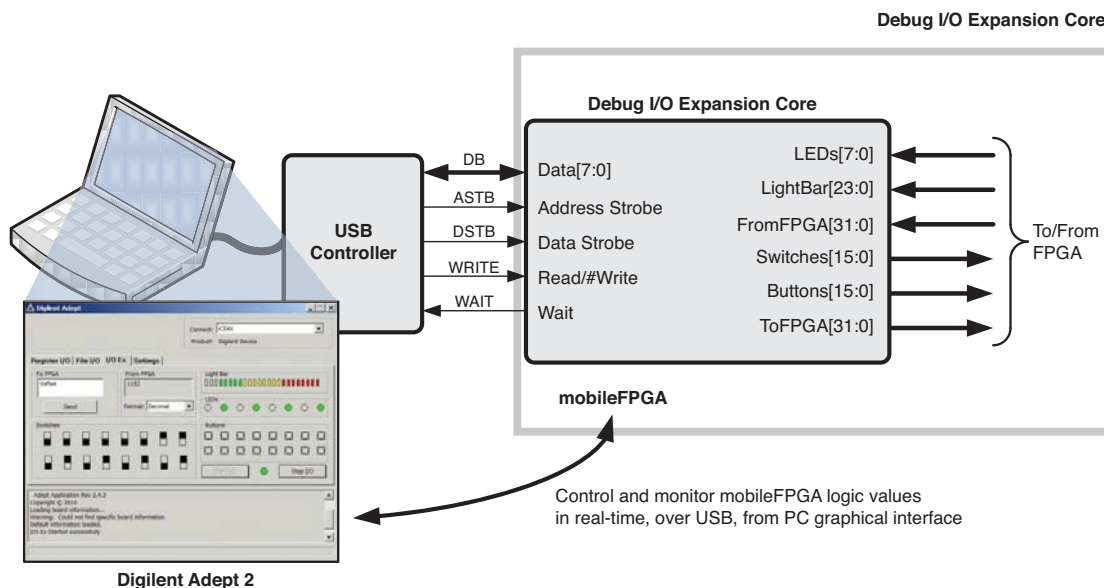
If no button was pressed during the last five seconds, the board returns to scrolling the LEDs.

The demonstration application is available for download from the Lattice website at:  
[www.latticesemi.com/iceblink40-hx1k](http://www.latticesemi.com/iceblink40-hx1k).

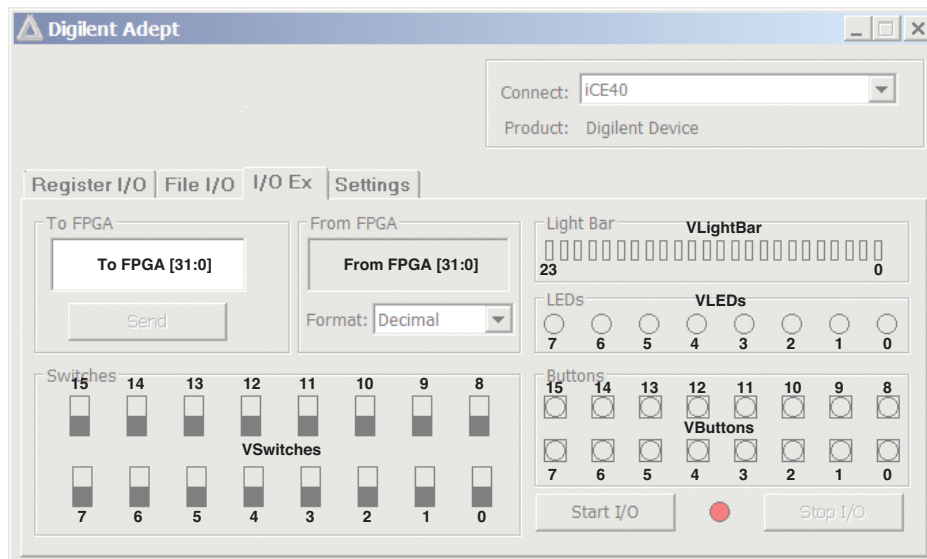
## Virtual I/O Expansion Debugging Interface

The iCEblink40 board is powered and programmed via the USB interface. Additionally, the USB interface also provides a convenient means to monitor and control logic inside the mobileFPGA, as shown in Figure 6. The USB controller drives a byte-wide parallel port expander implemented within the mobileFPGA, controlled by software running on the PC. The Digilent ADEPT2 I/O Expansion screen, shown in Figure 7, provides a mix of virtual switches, pushbuttons, LEDs, light bars, and 32-bit input and outputs.

**Figure 6. iCEblink40 Board Supports Virtual I/O Connections over USB**



**Figure 7. Digilent Adept 2 I/O Expansion Interface and mobileFPGA Connections**



## Using the Virtual I/Os in the Demo Application

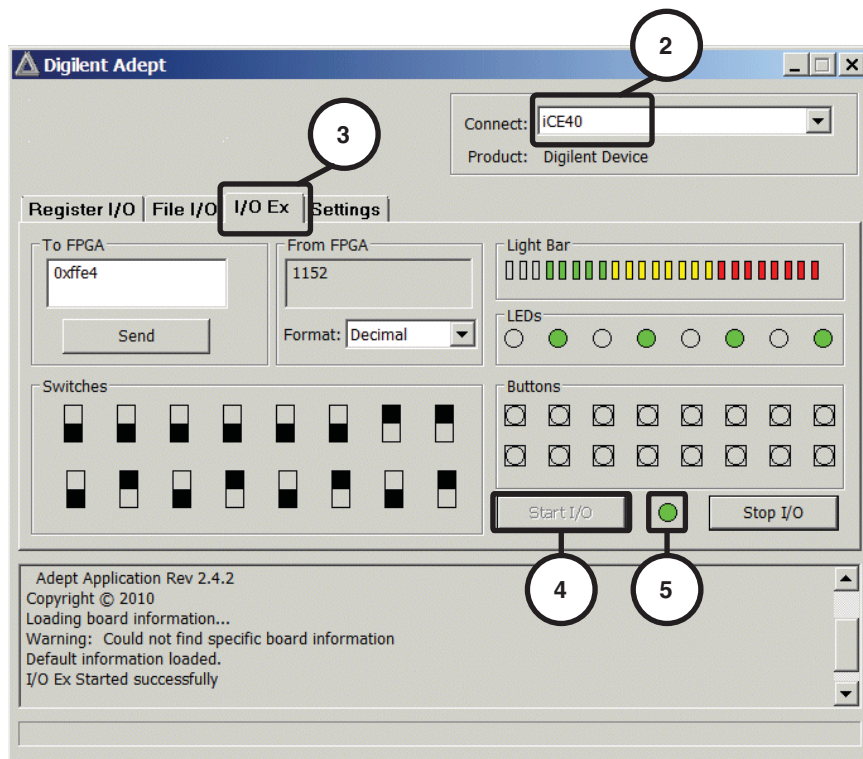
By default, the virtual I/Os are disconnected and the USB controller's I/O connections to the FPGA are high-impedance (Hi-Z).

To connect the virtual I/O, perform the following steps outlined in Figure 8.

1. From the Windows Start menu, select **Start > All Program > Digilent > Adept > Adept**.
2. Ensure that the Adept interface connects to the iCE40.
3. Click the **I/O Ex** tab.

4. Click **Start I/O**. Remember, the associated I/O Expander design must be part of the compiled FPGA design before the Virtual I/Os work.
5. If the virtual I/O expansion design is functioning correctly, the green virtual status LED will turn from red to green.

**Figure 8. Starting the Digilent Adept Virtual I/O Expansion Application**



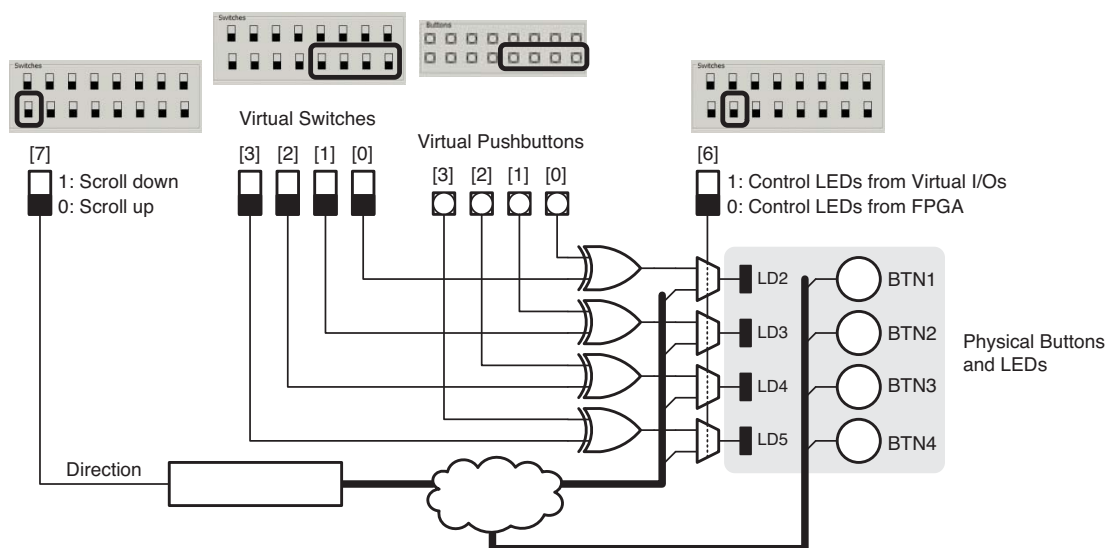
To disconnect the virtual I/O interface, simply click the **Stop I/O** button in the graphical interface.

## Controlling the Physical LEDs from Virtual I/Os in the Demonstration Design

When active, the virtual I/Os optionally control the physical LEDs on the board, as shown in Figure 9. For example, with the virtual I/Os active, change the position of virtual switch [7] (the bottom left switch in the graphical interface). Note how the physical LEDs on the board change direction.

Change virtual switch [6] to the up position. Now, the physical LEDs are controlled by the virtual switches [3:0] and virtual pushbuttons [3:0]. The values of the virtual switches are XORed together inside the FPGA. The virtual slide switches set a specific value for the physical LEDs. The pushbutton momentarily inverts the value while the virtual pushbutton is pressed in the graphical interface.

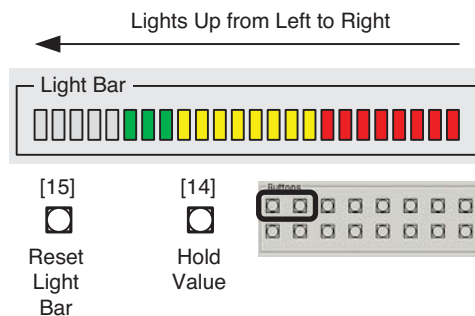
**Figure 9. Controlling the Physical LEDs from Virtual I/O**



## Controlling the Virtual Light Bar in the Demonstration Design

When the virtual I/Os are active, the virtual light bar lights up from left to right, controlled by logic inside the FPGA. The virtual pushbuttons [15] and [14] control the light bar. Pushbutton [15] resets the light bar, clearing all the lights. Pushbutton [14] forces the light bar to hold its current value.

**Figure 10. Controlling the Virtual Light Bar**



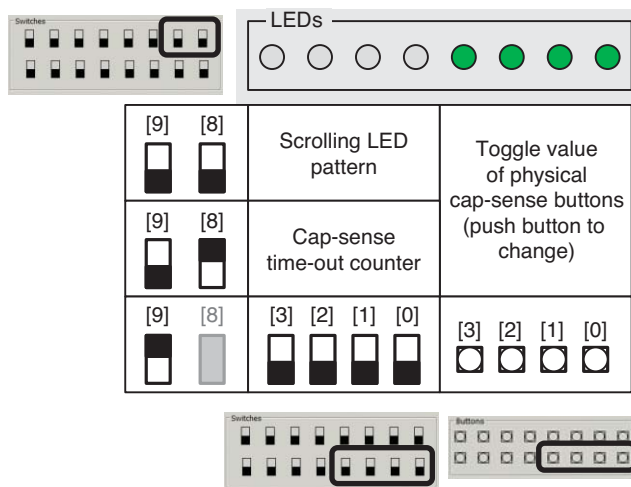
## Controlling the Virtual LEDs in the Demonstration Design

The virtual I/O interface includes eight, round, green LEDs, as shown in Figure 11. The values displayed on these virtual LEDs depends on the settings of virtual switches [9] and [8].

The eight LEDs are separated into left and right halves. When both virtual switches [9] and [8] are Low—the down position—the left LEDs echo the scrolling pattern of the LEDs, regardless if a physical cap-sense button was pressed. Use virtual switch [7] to reverse the direction of these LEDs. The right-most LEDs show the current toggle status of the four physical cap-sense buttons.

Changing virtual switch [8] to High—the up position—the four left-most LEDs then show the current value of the time-out counter than marks the five seconds after pressing a cap-sense button. Press a cap-sense button to reset the timer and note that the toggle status of the physical button changes on the right-most LEDs. The timer resets each time a physical button is pressed. Wait five seconds and the physical LEDs change back to the scrolling pattern.

Figure 11. Controlling the Virtual LEDs

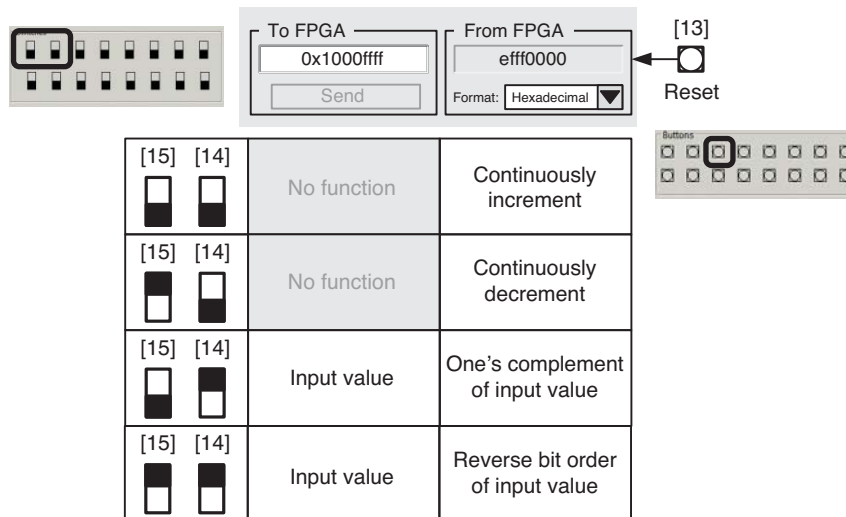


When virtual switch [9] is High—in the up position—then the left LEDs are controlled by virtual switches [3:0] and the right LEDs are controlled by virtual pushbuttons [3:0].

### Virtual Values to and from FPGA in the Demonstration Design

The virtual I/O interface also includes a 32-bit value from the FPGA logic and a 32-bit value to the FPGA logic, as shown in Figure 12. Two virtual switches, [14] and [15], control the behavior in of the virtual 32-bit values in the demonstration design.

Figure 12. Virtual Values to and from the FPGA



### Clocking Resources

The iCEblink40 board includes a Linear Technology LT1799 oscillator (X1 on the board and in the schematic) to generate a 3.33 MHz clock.

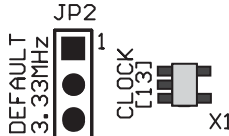
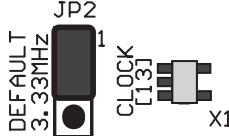
### FPGA Input

The output from the LT1799 oscillator feeds pin 13 of the iCE40HX1K mobileFPGA. FPGA pin 13 is also the global buffer input GBIN7.

## Supporting Other Frequencies

On the iCEblink40 board, the LT1799 produces a 3.3 MHz clock output by default. Other frequencies are possible via simple modifications of the board using the 1x3 connections on JP2, as listed in Table 2.

**Table 2. Selecting Other Oscillator Frequencies Using Jumper JP2**

| Clock Frequency    | JP2 Setting   | Jumper Position |
|--------------------|---|-----------------|
| 3.33 MHz (default) |  | None            |
| 333 kHz            |  | Upper Position  |
| 33.3 MHz           |   |                 |

**Table 4. User LED Connections**

| Designator | Location | mobileFPGA Pin | Header Connections |
|------------|----------|----------------|--------------------|
| LD2        | LD2 [59] | 59             | J12.1              |
| LD3        | LD3 [56] | 56             | J12.2              |
| LD4        | LD4 [53] | 53             | J12.3              |
| LD5        | LD5 [51] | 51             | J12.4              |

## Capacitive Touch Buttons

The iCEblink40 iCE40HX1K evaluation board has four capacitive-touch buttons, located toward the left side of the board, as shown in Figure 1. These buttons have dedicated connections only to the FPGA. These signals go nowhere else on the board and are not available on any of the breakout headers.

## FPGA Connections

Table 5 lists the four capacitive touch buttons on the iCEblink40 board and the associated mobileFPGA pins.

**Table 5. Capacitive Touch Buttons**

| Designator | Location  | mobileFPGA Pin |
|------------|-----------|----------------|
| BTN1       | BTN1 [60] | 60             |
| BTN2       | BTN2 [57] | 57             |
| BTN3       | BTN3 [54] | 54             |
| BTN4       | BTN4 [52] | 52             |

## Operation

Figure 13 shows the circuit used for each capacitive-touch button. Each button is attached to one I/O pin on the mobileFPGA. Each signal line includes a 100 k $\Omega$  pull-up resistor to 3.3V and a 100 pF capacitor down to ground.

**Figure 13. Example Capacitive Touch Button Circuit**

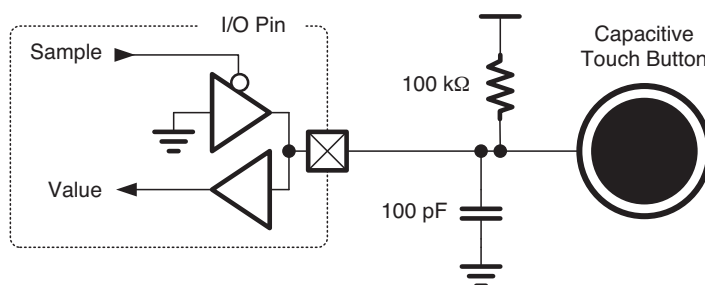
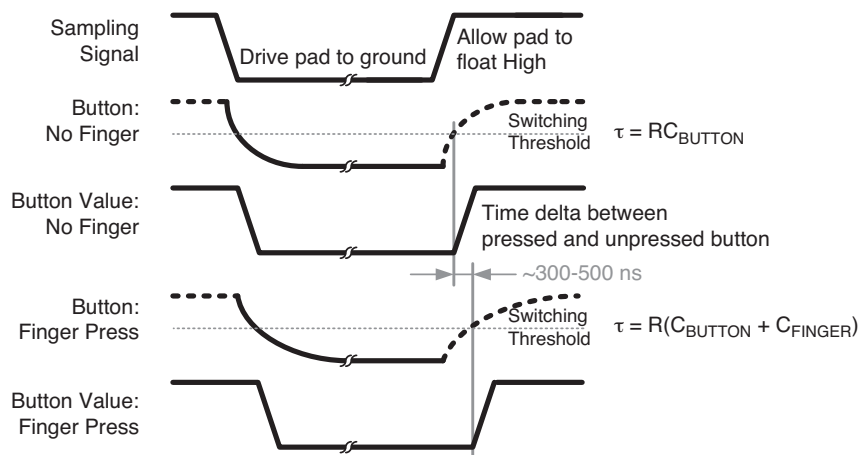


Figure 15 shows the general overall flowchart for the demonstration design to read the value on a capacitive touch button.

The sampling signal drives the voltage on the capacitive-touch button to ground in order to bleed of any residual charge as shown in Figure 14. After a period of time, depending on the button sample frequency, the button is allowed to float High.

Once the mobileFPGA output goes to Hi-Z (high-impedance, floating, three-state), the 100k $\Omega$  pull-up resistor to 3.3V charges the 100 pF capacitor. After about an RC time constant ( $\tau$  or tau), the voltage on the pad exceeds the input switching threshold of the mobileFPGA. A finger pressed against the capacitive-touch button adds about another 5 pF of capacitance, increasing the RC constant and delaying the Low-to-High transition for a pressed button.

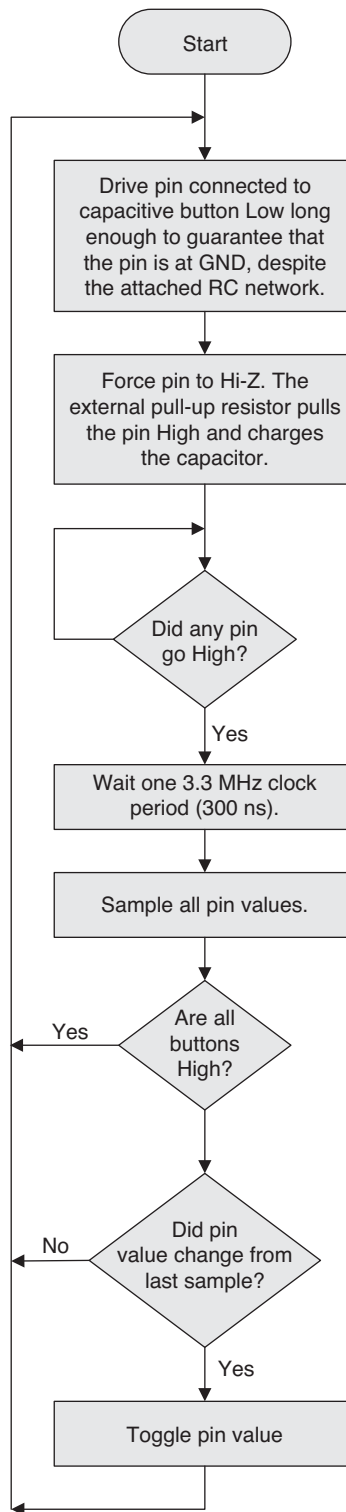
**Figure 14. Capacitive Touch Timing Examples**



The switching time difference between an unpressed and one or more pressed buttons is roughly 300 to 500 ns. Using the 3.33 MHz input, this amounts to a one clock delay difference between an unpressed and pressed buttons.

The simple circuit used on the iCEblink40 board detects simultaneous button presses on up to three of the capacitive-touch buttons. Pressing all four buttons is the same as pressing no buttons.

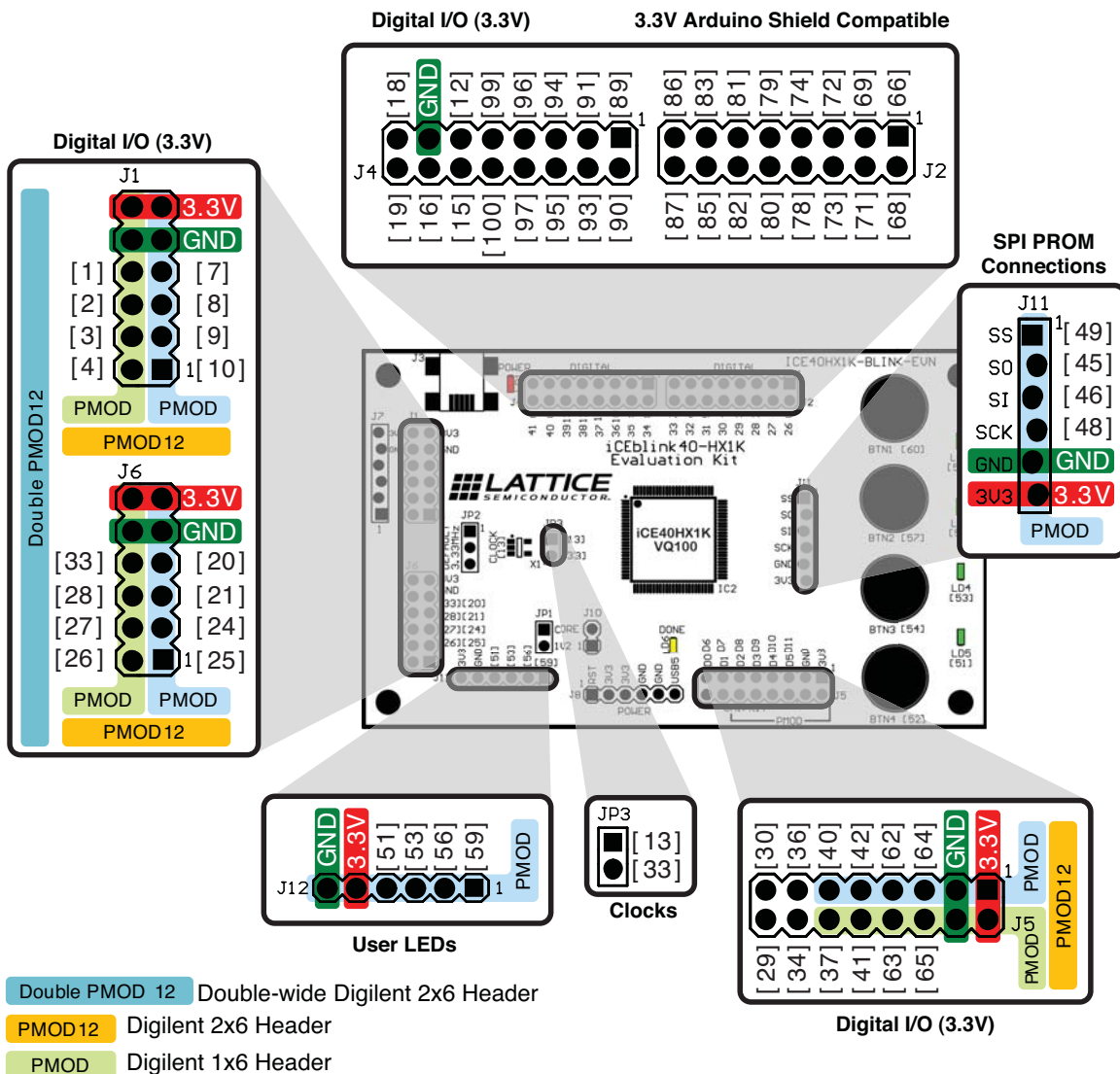
Figure 15. iCEblink40 Demo Application Capacitive Touch Button Flowchart



## User I/O Connections

Figure 16 shows the location of the 3.3V-compatible digital I/O connections on the iCEblink40 board. Each connection shows the pin number of the mobileFPGA I/O pin that attaches to the connection. Likewise, Table 6 lists the various I/O headers and their designed usage.

**Figure 16. Location of the 3.3V Digital I/O Connections and the mobileFPGA Pin Number**



**Table 6. Digital I/O Headers and Their Functions**

| I/O Header Group | Header Type            | Location                      | Function   |
|------------------|------------------------|-------------------------------|--|
| J2               | 2x8 0.1" centers       | Top edge, middle              | 3.3V digital I/O. Compatible with 3.3V Arduino Shield boards.  |
| J4               | 2x8 0.1" centers       | Top edge, left side           | 3.3V digital I/O. Compatible with 3.3V Arduino Shield boards.  |
| J1               | 2x6 0.1 centers        | Left edge, top                | 3.3V digital I/O. 3.3V digital I/O. Compatible with Digilent 1x6 and 2x6 PMod modules. Also supports double PMod12 modules when used with header J6. |
| J6               | 2x6 0.1 centers        | Left edge bottom              | 3.3V digital I/O. Compatible with Digilent 1x6 and 2x6 PMod modules. Also supports double PMod12 modules when used with header J1.                   |
| J7               | 1x6 0.1 centers offset | Left edge, top                | Production programming of USB controller.  |
| J11              | 1x6 0.1 centers offset | Middle, toward left           | 3.3V digital I/O. Connections between the mobile FPGA and the SPI PROM. Compatible with Digilent 1x6 PMod modules.                                   |
| J5               | 2x8 0.1" centers       | Bottom edge, right side       | 3.3V digital I/O. Portions compatible with Digilent 1x6 and 2x6 PMod modules. Portions also compatible with 3.3V Arduino Shield boards.              |
| JP3              | 1x2 0.1" centers       | Middle, to left of mobileFPGA | 3.3V digital I/O. Clock connections from the LTC1799 oscillator (GBIN7) and possible into GBIN2.   |
| J12              | 1x6 0.1" centers       | Bottom edge, left side        | 3.3V digital I/O. Connections to the user LED I/O. Compatible with Digilent 1x6 Pmod modules.  |

## Supported Pmod Peripheral Modules

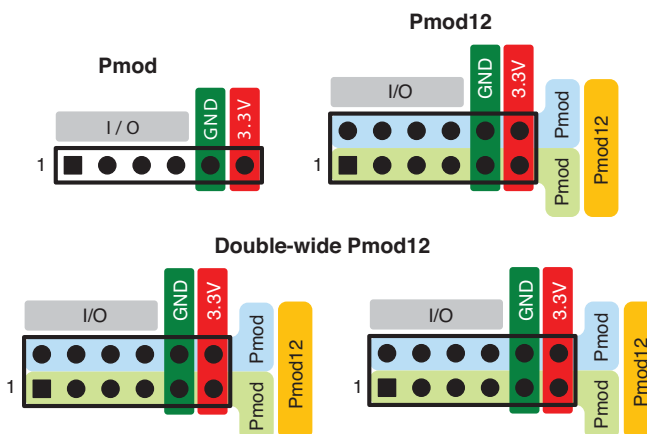
As shown in Figure 16, the iCEblink40 board supports a variety of Pmod peripheral modules for easy I/O expansion. Table 7 lists the 0.1" through-hole headers on the iCEblink40 board that support Pmod modules. Pmod modules come in a few different form factors and each Pmod header includes power and ground supplies. Figure 17 shows the how the different Pmod form factors interrelate. The easiest way to support a Pmod module is to add the appropriate female socket listed, or an equivalent. Straight-through or right-angle through-hole sockets are listed. Male headers are also possible solutions when using the interface cable provided with most Pmod modules.

**Table 7. Pmod Module Headers**

| Header  | Type   | Female Socket (Manufacturer/Part Number)      |   |
|---------|--|---|---|
|         |  | Straight-through                              | Right-angle                                   |
| J1, J12 | 2x6 header on 0.1" centers. Each is a Pmod12 header that supports two six-pin Pmod modules. Both together form a double-wide Pmod connection.  | Sullins Connector Solutions<br>PPPC062LFBN-RC | Sullins Connector Solutions<br>PPPC062LJBN-RC |
| J5      | 2x8 header on 0.1" centers. The left side of header J5 forms a Pmod12 header, as shown in Figure 16. A 2x6 header similar to J1, J12 can also be used but must be mounted toward the right end of the holes as marked. | Sullins Connector Solutions<br>PPPC082LFBN-RC | Sullins Connector Solutions<br>PPPC082LJBN-RC |

As shown in Figure 17, a Pmod module has six connections—four I/O plus power and ground. A Pmod12 module has 12 connections and the module is effectively two six-pin Pmod modules stacked together. Finally, a double-wide Pmod12 consists of two Pmod12 headers spaced apart. Most of the Pmod modules also include interface cables to allow easy connection to other header types.

Figure 17. Pmod Module Types



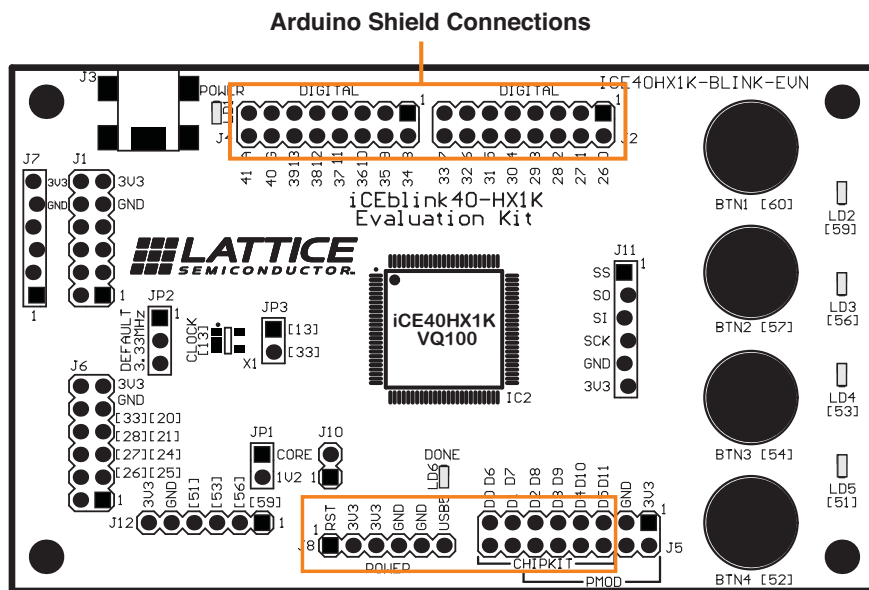
For a complete list of Pmod peripheral modules, visit the Digilent web site.

[www.digilentinc.com/Products/Catalog.cfm?NavPath=2.401&Cat=9](http://www.digilentinc.com/Products/Catalog.cfm?NavPath=2.401&Cat=9)

## Arduino Shield Board Support

The iCEblink40 board also mechanically and electrically supports select 3.3V Arduino Shield boards popular in the microcontroller development community. The Shield connections are located on headers J4, J2, J8 and a portion of J5 as shown in Figure 18. Headers jumper J4 and J2 are 3.3V digital I/O connections. Header J8 provides power connections to the Shield board. The left side of header J5 also provides 3.3V digital I/O but the 3.3V and GND connections do not connect to the Shield board.

Figure 18. Arduino Shield Board Connections



## Required Header Sockets

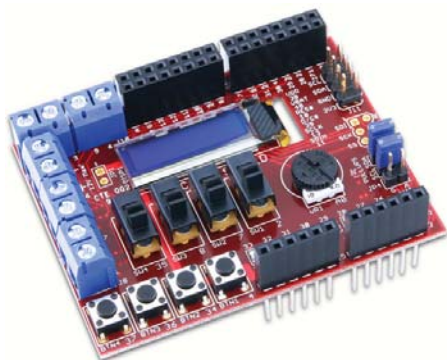
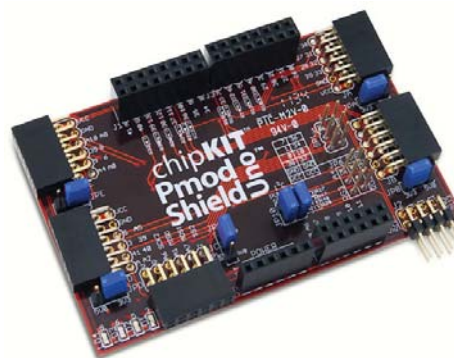
To support Arduino Shield boards, the indicated headers must be loaded with female socket headers on 0.1" headers, as listed in Table 19.

**Table 8. Sockets to Support Arduino Shield Boards**

| Header(s)  | Description                              | Quantity | Manufacturer/Part Number                      |
|------------|--|----------|---|
| J2, J4, J5 | 2x8 female header socket on 0.1" centers | 3        | Sullins Connector Solutions<br>PPPC082LFBN-RC |
| J8         | 1x6 female header socket on 0.1" centers | 1        | Sullins Connector Solutions<br>PPPC061LFBN-RC |

## Tested Arduino Boards

Figure 19 shows the Arduino Shield boards have been tested for basic compatibility. Other Arduino Shield boards may also be compatible.

**Figure 19. Compatible Arduino Shield Boards**

**chipKITBasic I/O Shield**

**chipKIT Pmod Shield-Uno**

## USB Interface

The iCEblink40 board is powered by connecting the board to a computer USB port, a power USB hub, or a USB-based AC adapter, commonly used in consumer electronics. A typical USB port provides up to 500 mA at 5V, providing up to 2.5W of total power. The iCE40HX1K consumes SIGNIFICANTLY LESS power, even when operating at full performance. However, be careful when using the board to power off-board peripheral funds.

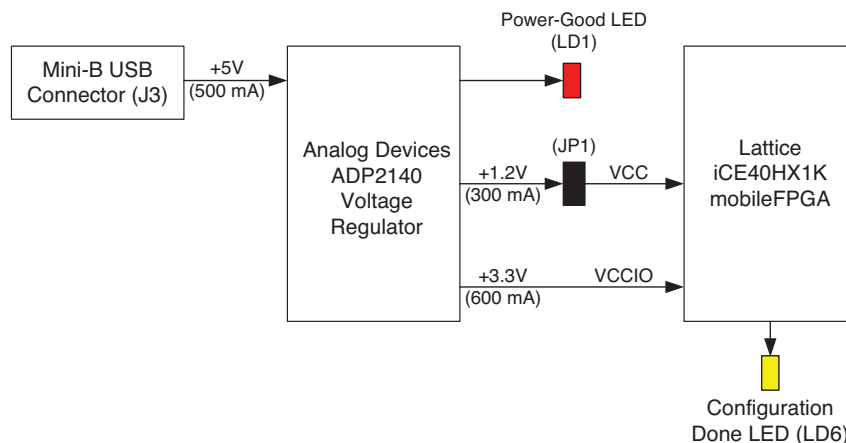
## Connector

The USB connector to the board is located in the upper left corner, labeled J3. The board connects using a standard USB cable with a male mini-B connector.

## Power Supply

Figure 20 shows the iCEblink40 power supply circuit that derives power from the USB mini-B connector (J3). The USB connector provides up to 500 mA at +5V DC. An Analog Devices ADP2140 regulator generates +1.2V for the mobileFPGA core VCC and +3.3V for all I/O connections. The regulator also indicates when power is good and lights up the red power-good LED (LD1).

**Figure 20. iCEblink40 USB Power Supply Circuit**



Jumper JP1 provides a convenient location from which to measure core power to the mobileFPGA.

## SPI Flash Programming

The USB interface also provides Flash programming for the on-board SPI PROM, as described in “Programming the iCEblink40 Board” below.

### Digilent Parallel Port (DPP)

The Digilent Parallel Port (DPP) interface is used for virtual I/O and debugging using a USB connection to the board from a Windows PC. See [“Virtual I/O Expansion Debugging Interface” on page 5](#) for additional information.

## 1Mbit SPI Configuration PROM

The configuration bitstream for the iCE40 mobileFPGA is stored in a M25P10A 1Mbit SPI serial Flash PROM. The PROM is large enough to hold two configuration images and supports the iCE40 WarmBoot feature, if so enabled within the FPGA application. The PROM is physically located on the back side of the board.

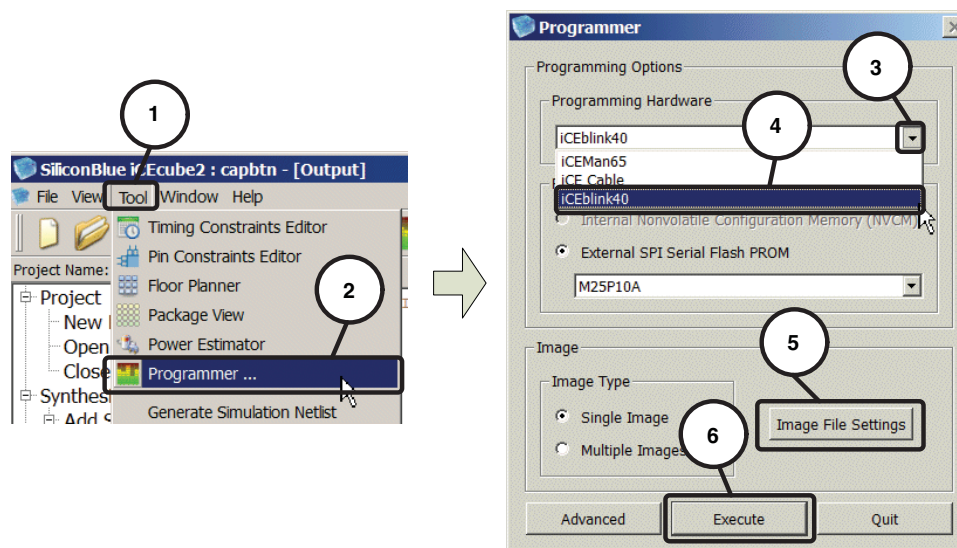
## Programming the iCEblink40 Board


The iCEblink40 board includes on-board USB-based programming support either from the Lattice iCEcube2 software or using a command from a console window or DOS box.

### From iCEcube2

Figure 21 shows the command sequence for programming the SPI Flash PROM on the iCEblink40 board using the iCEcube2 development software.

Figure 21. Programming the iCEblink40 Board from iCEcube2



1. Select **Tool > Programmer** from the iCEcube2 menu bar.
2. Click the dropdown button (  ) under **Programming Hardware**.
3. Select **iCEblink40**.
4. The bitstream file should already be set appropriately based on the iCEcube2 project settings. If not, click **Image Files Settings** to select the configuration bitstream file.
5. Click **Execute** to program the iCEblink40 board.

If all is working correctly, the power-on LED and the configuration done LED will both go out momentarily as iCEcube2 programs the on-board SPI Flash PROM. After programming is complete, both LEDs should light up again and the mobileFPGA will execute the new configuration image.

## From Command Line

The iCEblink40 programming software can also be executed from a console window or DOS box. To open a console window or DOS box, click the **Start** button and type **cmd** in the textbox immediately above the Start button.

### Executable Location

After installation, the programming software executable is called **iceutil.exe** and is located in the **\Sbt-Tools\sbt\_backend\bin\win32\opt** directory. The iceutil.exe executable can be copied into the same directory as the mobileFPGA bitstream image or can be pointed to on the command line.

### mobileFPGA Bitstream Configuration File

The required bitstream image is part of the iCEcube2 project. Multiple versions of the bitstream are stored in the **<projname>\_implmnt\sbt\outputs\bitmap** directory. The raw hexadecimal version of the bitstream is called **<projname>\_bitmap.hex**. The alternate format of the same information is an Intel hexadecimal file called **<projname>\_bitmap\_int.hex**.

### Raw Hexadecimal Command Example

```
<path>/iceutil -d ice40 -res -cr -m M25P10A -fh -w <path/projname>_bitmap.hex
```

### Intel Hexadecimal Command Example

```
<path>/iceutil -d ice40 -res -cr -m M25P10A -fi -w <path/projname>_bitmap_int.hex
```

## Help

<path>/iceutil -help

## Testing Core Power

Jumper JP1 provides the ability to measure core power consumption by the mobileFPGA. Two power measurement methods are supported.

*Note: The iCEblink40 HX1K evaluation board uses an early version of the iCE40HX1K silicon that has higher than expected static current consumption. Although the demonstration application consumes less than 500  $\mu$ A, the production silicon will consume even less current. Similarly, the lower power iCE40LP1K devices use even less power than the iCE40HX1K mobileFPGA.*

## Easy Method Using a Multimeter

Connect the iCEblink40 board through your high-accuracy multimeter. Use a meter with a minimum of 10,000 counts; 50,000 counts or more is recommended for better accuracy.

To take a quick measurement, follow these steps.

1. Disconnect power to the iCEblink40 board by removing the USB cable connection, either at the board or at the computer.
2. Remove the jumper JP1, which isolates the mobileFPGA's core supply from the 1.2V supply on the board.
3. Connect your multimeter's alligator or test clips to the stake pins on header JP1.
4. Configure the multimeter to measure current using its highest mA or Amp range. This setting typically has the lowest voltage drop internally within the meter.
5. Re-connect the USB cable that supplies power to the iCEblink40 board and configure the mobileFPGA device if necessary.
6. Observe the power reading on the multimeter. At low clock rates, which results in lower power consumption, switch the meter to a lower amperage setting for better accuracy. However, this also may increase the resistance across the meter leads. Using too low of a meter setting causes a large voltage drop within the meter, potentially violating the minimum input voltage specification to the mobileFPGA device.
7. The value measured by the multimeter is a current. Convert the measurement to power using Equation 1. The voltage is the operating voltage, the voltage across the jumper. This value can be accurately measured with a second multimeter to show the voltage drop across the first. However, just measuring the initial voltage, before taking any current readings, usually provides acceptable accuracy and the voltage drop across the meter is generally small.

$$Power = Current \times Voltage \quad (1)$$

Although this method is easy, here are a few caveats and pointers.

- **Always start at the highest current setting for your meter. Using too small a setting may damage your meter!** After determining the maximum current range for your measurement, then you can safely use the appropriate lower current setting.
- The voltage drop across the meter leads may violate the minimum supply voltage specification for the mobileFPGA device. To determine the voltage drop, use a second multimeter to measure either the voltage across the first meter's leads during a test or the resistance between the first meter's leads.
- Using the highest current measurement setting typically results in the lowest voltage drop.

## Using High-Precision, Small-Value Resistors

For more-accurate, time-sensitive measurements, place a low-value resistor across the jumper test point. According to Ohm's Law, the current passing through the resistor produces a voltage drop. Measure the voltage differential across the resistor during expected operation. Convert the measurement to power using Equation 2. The voltage is the measured voltage across the resistor; the resistance is the value of the resistor.

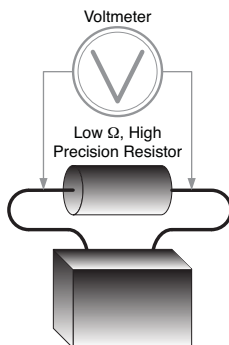
$$Power = \frac{(Voltage)^2}{Resistance} \quad (2)$$

The following are a few guidelines on selecting a resistor.

- Use a high-precision resistor.
- The resistor must handle the power dissipated under the anticipated test conditions.
- Too small a resistor value may result in too small a voltage difference across the resistor to measure with your test equipment.
- Too large a resistor value may result in too large of a voltage difference across the resistor. Too large a voltage drop might violate the minimum voltage specifications for the mobileFPGA device.

Figure 22 shows an example header block designed to fit over one of the jump locations. Measure the voltage drop across the low-value resistor, either with a voltmeter or with data acquisition equipment.

**Figure 22. Resistor Header Block**

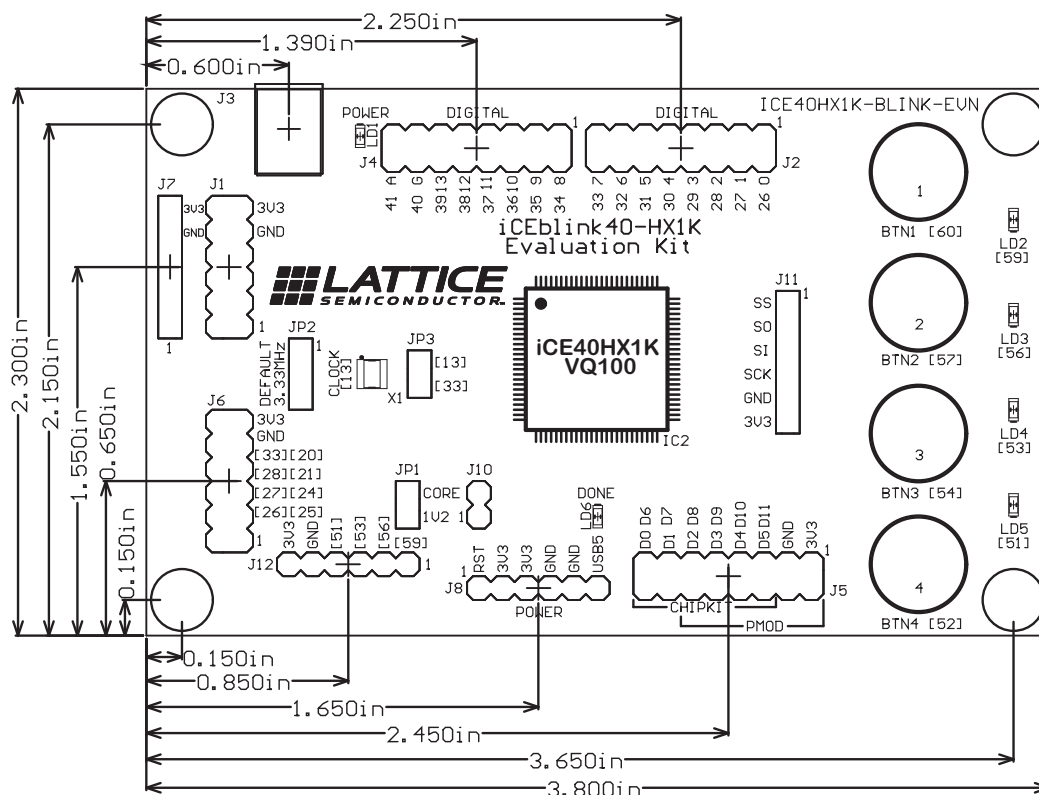


This method is recommended for taking power measurements over time.


## Mechanical Specifications

Figure 23 shows the mechanical dimensions for the iCEblink40 board, including the location of the four mounting holes. With a jumper installed on JP1, the board height is approximately 0.700 inches high, including the four rubber feet mounted on the bottom side of the board.

**Figure 23. iCEblink40 HX1K Board Mechanical Dimension**



## Ordering Information

| Description                    | Ordering Part Number | China RoHS Environment-Friendly Use Period (EFUP)                                     |
|--------------------------------|----------------------|---|
| iCEblink40-HX1K Evaluation Kit | ICE40HX1K-BLINK-EVN  |  |

## Technical Support Assistance

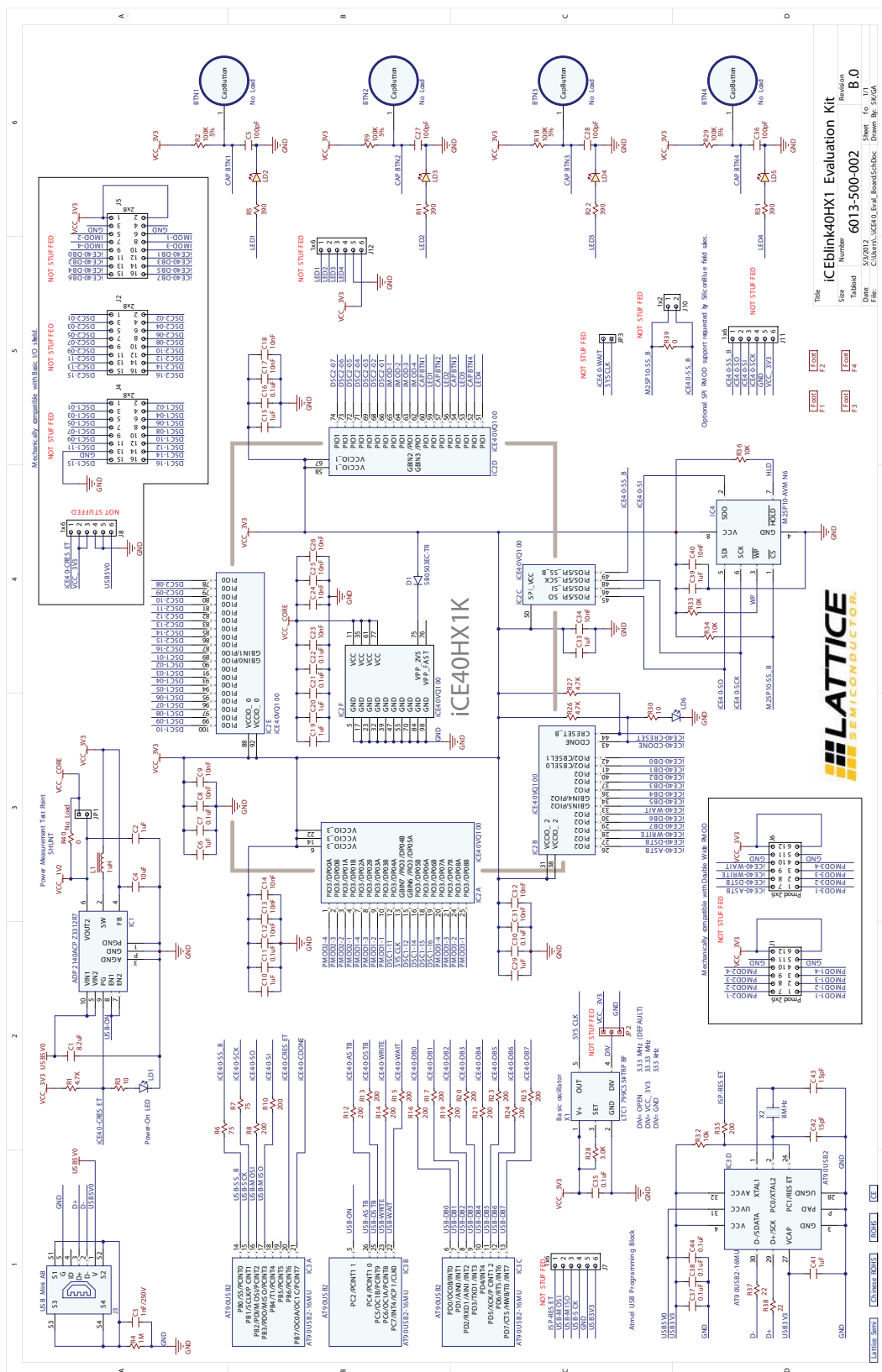
Hotline: 1-800-LATTICE (North America)  
+1-503-268-8001 (Outside North America)  
e-mail: [techsupport@latticesemi.com](mailto:techsupport@latticesemi.com)  
Internet: [www.latticesemi.com](http://www.latticesemi.com)

## Revision History

| Date     | Version | Change Summary   |
|----------|---------|------------------|
| May 2012 | 01.0    | Initial release. |

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**Figure 24. Schematic**



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## Appendix B. Bill of Materials (Major Components)

**Table 9. Bill of Materials**

| Reference | Vendor                | Part Number                       | Description                                   |
|-----------|-----------------------|-----------------------------------|---|
| IC2       | Lattice Semiconductor | <a href="#">iCE40HX1K-VQ100</a>   | iCE40 HX-series mobileFPGA                    |
| IC1       | Analog Devices        | <a href="#">ADP2140ACPZ3312R7</a> | Low-quiescent buck/LDO regulator (1.2V, 3.3V) |
| X1        | Linear Technology     | <a href="#">LTC1799CS5#TRPBE</a>  | Oscillator                                    |
| IC4       | Micron Technology     | <a href="#">M25P10-AVMN6</a>      | 1Mbit SPI serial configuration Flash PROM     |
| IC3       | Atmel Corporation     | <a href="#">AT90USB162-16MU</a>   | USB programming and debugging interface       |